

# 74HC164-Q100; 74HCT164-Q100

8-bit serial-in, parallel-out shift register

Rev. 1 — 16 August 2013

Product data sheet

## 1. General description

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The 74HC164-Q100; 74HCT164-Q100 is an 8-bit serial-in/parallel-out shift register. The device features two serial data inputs (DSA and DSB), eight parallel data outputs (Q0 to Q7). Data is entered serially through DSA or DSB and either input can be used as an active HIGH enable for data entry through the other input. Data is shifted on the LOW-to-HIGH transitions of the clock (CP) input. A LOW on the master reset input (MR) clears the register and forces all outputs LOW, independently of other inputs. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Input levels:
  - ◆ For 74HC164-Q100: CMOS level
  - ◆ For 74HCT164-Q100: TTL level
- Gated serial data inputs
- Asynchronous master reset
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Multiple package options

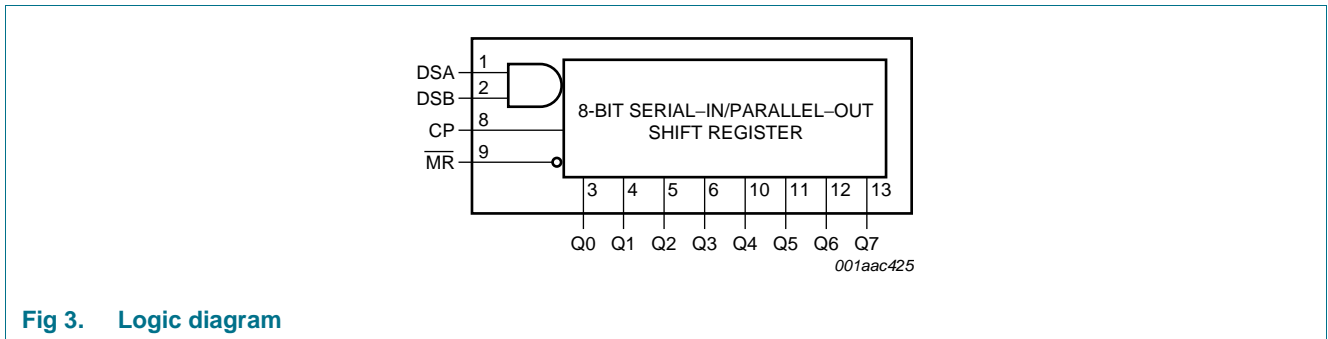
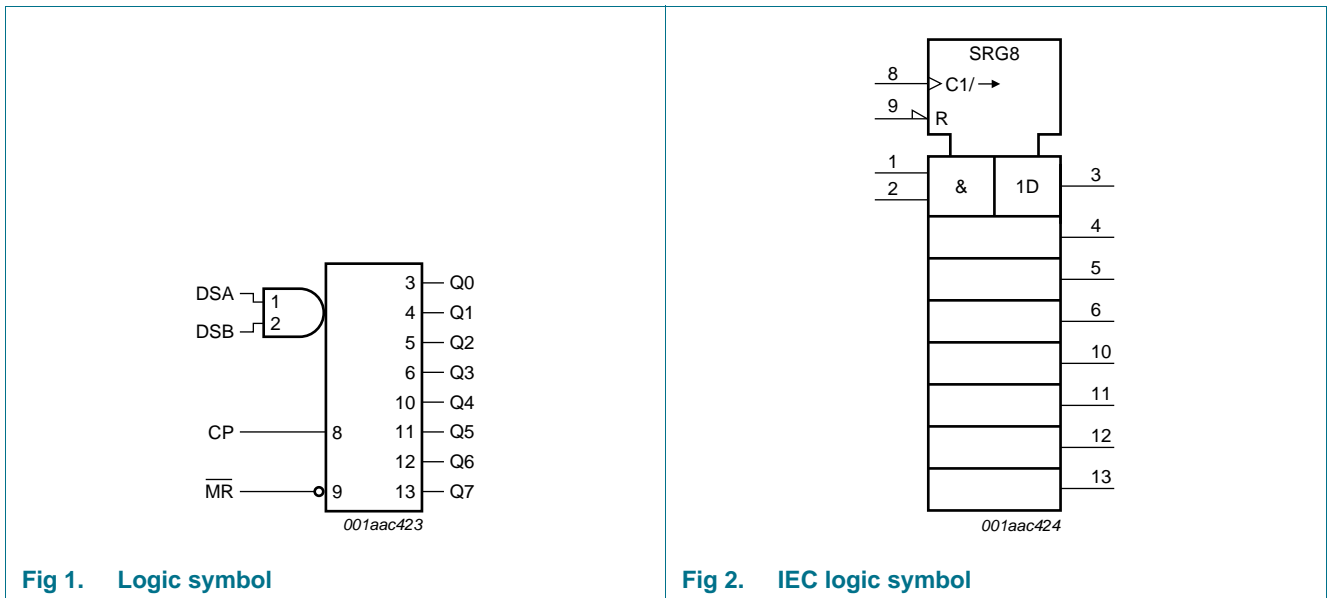


### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74HC164D-Q100 74HCT164D-Q100	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HC164PW-Q100 74HCT164PW-Q100	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74HC164BQ-Q100 74HCT164BQ-Q100	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

### 4. Functional diagram



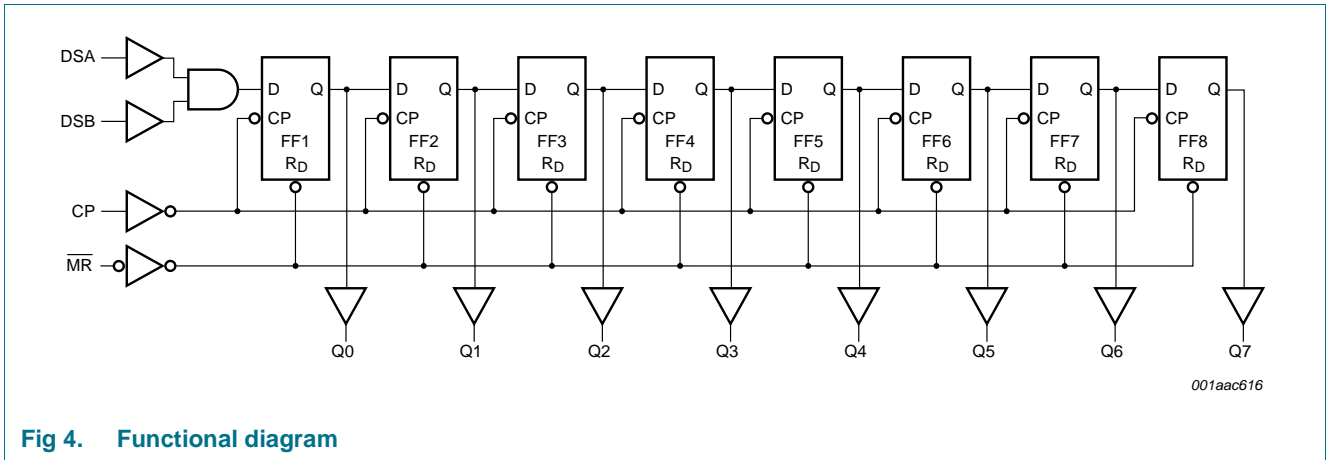


Fig 4. Functional diagram

## 5. Pinning information

### 5.1 Pinning

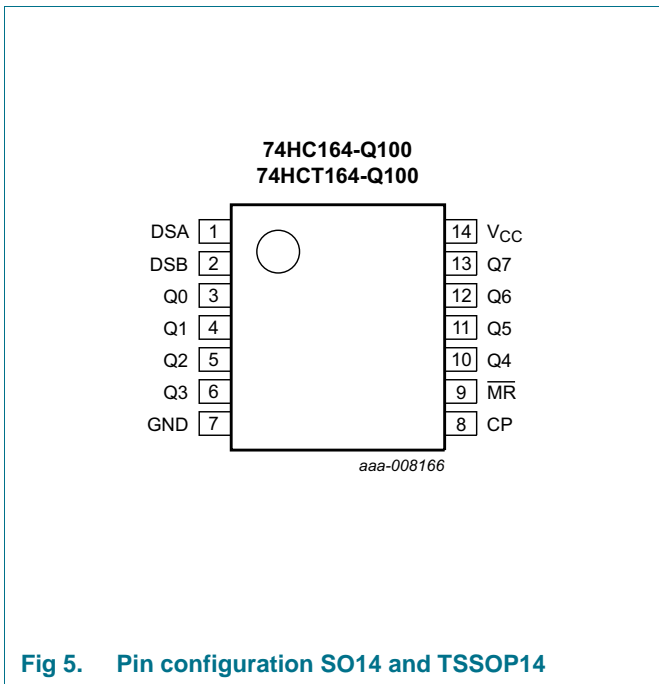


Fig 5. Pin configuration SO14 and TSSOP14

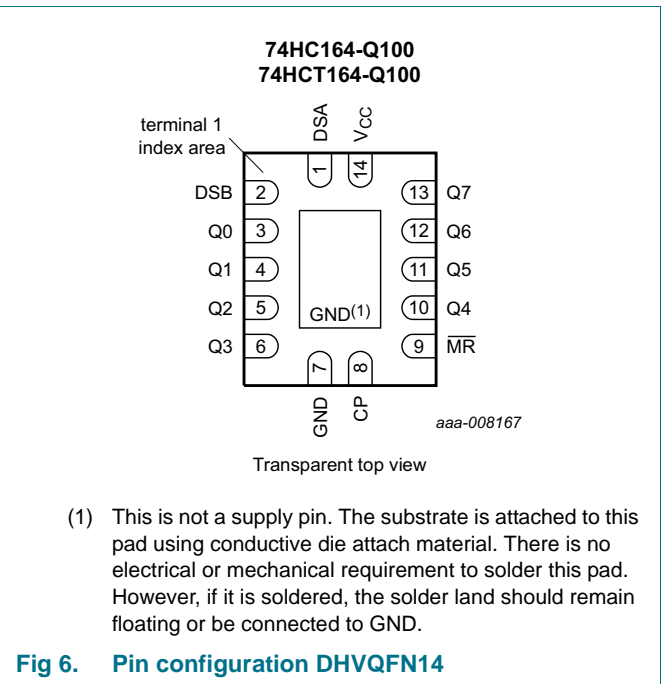


Fig 6. Pin configuration DHVQFN14

## 5.2 Pin description

**Table 2.** Pin description

Symbol	Pin	Description
DSA	1	data input
DSB	2	data input
Q0 to Q7	3, 4, 5, 6, 10, 11, 12, 13	output
GND	7	ground (0 V)
CP	8	clock input (LOW-to-HIGH, edge-triggered)
$\overline{\text{MR}}$	9	master reset input (active LOW)
V <sub>CC</sub>	14	positive supply voltage

## 6. Functional description

**Table 3.** Function table<sup>[1]</sup>

Operating modes	Input				Output	
	$\overline{\text{MR}}$	CP	DSA	DSB	Q0	Q1 to Q7
Reset (clear)	L	X	X	X	L	L to L
Shift	H	↑	l	l	L	q0 to q6
	H	↑	l	h	L	q0 to q6
	H	↑	h	l	L	q0 to q6
	H	↑	h	h	H	q0 to q6

[1] H = HIGH voltage level  
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition  
 L = LOW voltage level  
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition  
 q = lower case letters indicate the state of the referenced input one set-up time prior to the LOW-to-HIGH clock transition  
 ↑ = LOW-to-HIGH clock transition

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	[1] -	±20	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	[1] -	±20	mA
$I_O$	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	±25	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation		[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

For TSSOP14 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

For DHVQFN14 packages:  $P_{tot}$  derates linearly with 4.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC164-Q100			74HCT164-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC164-Q100</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
		I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT164-Q100</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
V <sub>OL</sub>	LOW-level output voltage	I <sub>O</sub> = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
I <sub>I</sub>	input leakage current	I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1	-	±1	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; I <sub>O</sub> = 0 A; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V	-	100	360	-	450	-	490	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**GND = 0 V; t<sub>r</sub> = t<sub>f</sub> = 6 ns; C<sub>L</sub> = 50 pF; test circuit, see [Figure 10](#); unless otherwise specified

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	

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t <sub>pd</sub>	propagation delay	CP to Qn; see <a href="#">Figure 7</a> <sup>[1]</sup>								
		V <sub>CC</sub> = 2.0 V	-	41	170	-	215	-	255	ns
		V <sub>CC</sub> = 4.5 V	-	15	34	-	43	-	51	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	12	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	12	29	-	37	-	43	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	MR to Qn; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 2.0 V	-	39	140	-	175	-	210	ns
		V <sub>CC</sub> = 4.5 V	-	14	28	-	35	-	42	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	11	24	-	30	-	36	ns
t <sub>t</sub>	transition time	see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 2.0 V	-	19	75	-	95	-	110	ns
		V <sub>CC</sub> = 4.5 V	-	7	15	-	19	-	22	ns
		V <sub>CC</sub> = 6.0 V	-	6	13	-	16	-	19	ns
t <sub>w</sub>	pulse width	CP HIGH or LOW; see <a href="#">Figure 7</a>								
		V <sub>CC</sub> = 2.0 V	80	14	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	5	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	4	-	17	-	20	-	ns
		MR LOW; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 2.0 V	60	17	-	75	-	90	-	ns
		V <sub>CC</sub> = 4.5 V	12	6	-	15	-	18	-	ns
		V <sub>CC</sub> = 6.0 V	10	5	-	13	-	15	ns	

**Table 7. Dynamic characteristics ...continued**  
*GND = 0 V;  $t_r = t_f = 6$  ns;  $C_L = 50$  pF; test circuit, see [Figure 10](#); unless otherwise specified*

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{rec}$	recovery time	$\overline{MR}$ to CP; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V	60	17	-	75	-	90	-	ns
		$V_{CC} = 4.5$ V	12	6	-	15	-	18	-	ns
		$V_{CC} = 6.0$ V	10	5	-	13	-	15	-	ns
$t_{su}$	set-up time	DSA, and DSB to CP; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	60	8	-	75	-	90	-	ns
		$V_{CC} = 4.5$ V	12	3	-	15	-	18	-	ns
		$V_{CC} = 6.0$ V	10	2	-	13	-	15	-	ns
$t_h$	hold time	DSA, and DSB to CP; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	+4	−6	-	4	-	4	-	ns
		$V_{CC} = 4.5$ V	+4	−2	-	4	-	4	-	ns
		$V_{CC} = 6.0$ V	+4	−2	-	4	-	4	-	ns
$f_{max}$	maximum frequency	for Cp, see <a href="#">Figure 7</a>								
		$V_{CC} = 2.0$ V	6	23	-	5	-	4	-	MHz
		$V_{CC} = 4.5$ V	30	71	-	24	-	20	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	78	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	per package; $V_I = GND$ to $V_{CC}$	[3]	-	40	-	-	-	-	pF

### 74HCT164-Q100

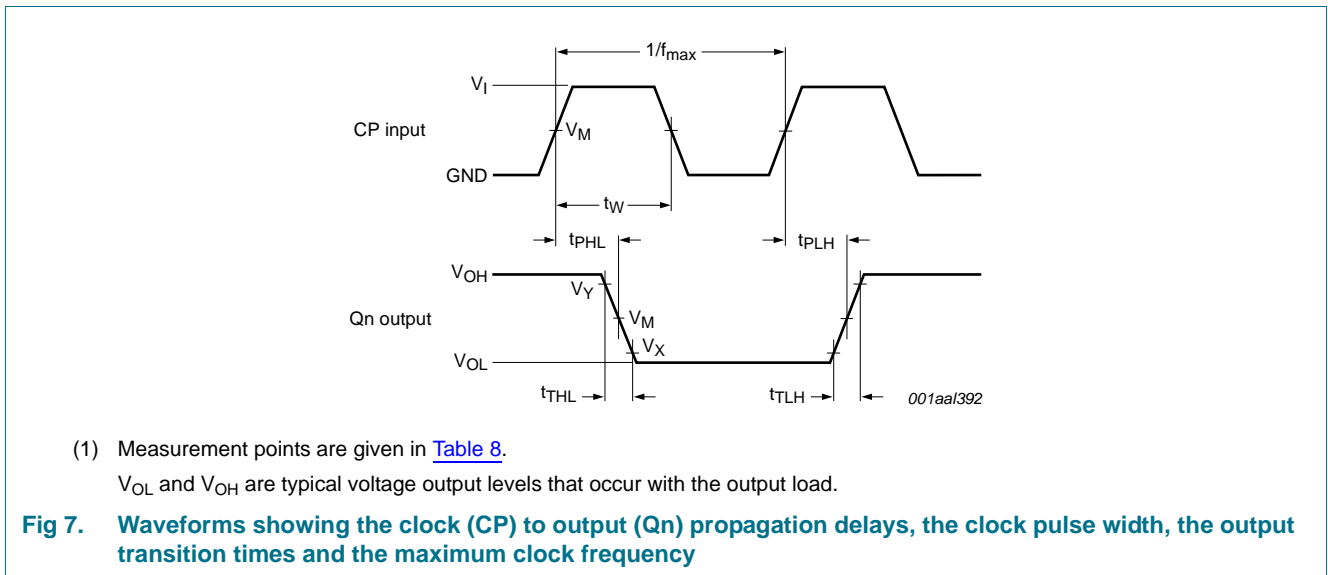
$t_{pd}$	propagation delay	CP to Qn; see <a href="#">Figure 7</a> [1]								
		$V_{CC} = 4.5$ V	-	17	36	-	45	-	54	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
$t_{PHL}$	HIGH to LOW propagation delay	$\overline{MR}$ to Qn; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V	-	19	38	-	48	-	57	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	16	-	-	-	-	-	ns
$t_t$	transition time	see <a href="#">Figure 7</a> [2]								
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
$t_W$	pulse width	CP HIGH or LOW; see <a href="#">Figure 7</a>								
		$V_{CC} = 4.5$ V	18	7	-	23	-	27	-	ns
		MR LOW; see <a href="#">Figure 8</a>								
$t_{rec}$	recovery time	$V_{CC} = 4.5$ V	18	10	-	23	-	27	-	ns
		$\overline{MR}$ to CP; see <a href="#">Figure 8</a>								
$t_{su}$	set-up time	$V_{CC} = 4.5$ V	16	7	-	20	-	24	-	ns
		DSA, and DSB to CP; see <a href="#">Figure 9</a>								
$t_{su}$	set-up time	$V_{CC} = 4.5$ V	12	6	-	15	-	18	-	ns



**Table 7. Dynamic characteristics ...continued**  
*GND = 0 V;  $t_r = t_f = 6 \text{ ns}$ ;  $C_L = 50 \text{ pF}$ ; test circuit, see [Figure 10](#); unless otherwise specified*

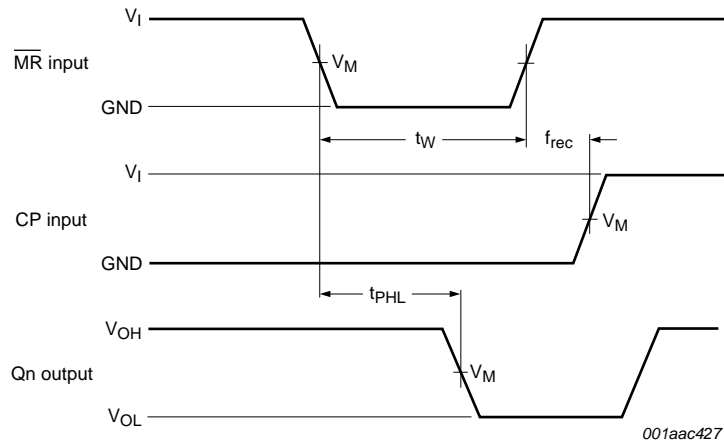
Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_h$	hold time	DSA, and DSB to CP; see <a href="#">Figure 9</a> $V_{CC} = 4.5 \text{ V}$	+4	−2	-	4	-	4	-	ns
$f_{max}$	maximum frequency	for Cp, see <a href="#">Figure 7</a> $V_{CC} = 4.5 \text{ V}$	27	55	-	22	-	18	-	MHz
		$V_{CC} = 5.0 \text{ V}$ ; $C_L = 15 \text{ pF}$	-	61	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC} - 1.5 \text{ V}$	[3]	40	-	-	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ):  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.



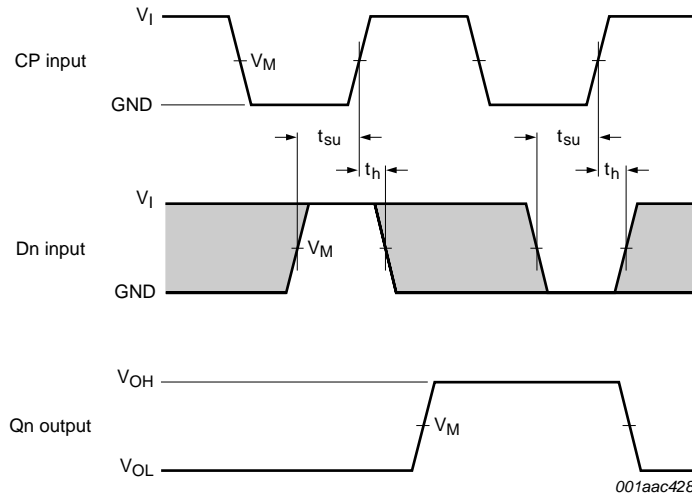
**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC164-Q100	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT164-Q100	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



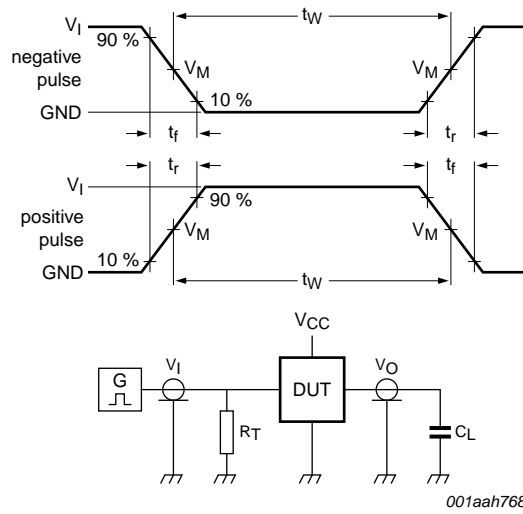
- (1) Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. Waveforms showing the master reset ( $\overline{MR}$ ) pulse width, the master reset to output ( $Q_n$ ) propagation delays and the master reset to clock ( $CP$ ) removal time**



- (1) Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.  
 The shaded areas indicate when the input is permitted to change for predictable output performance.

**Fig 9. Waveforms showing the data set-up and hold times for  $D_n$  inputs**



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

**Fig 10. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC164-Q100	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$
74HCT164-Q100	3.0 V	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

## 11. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

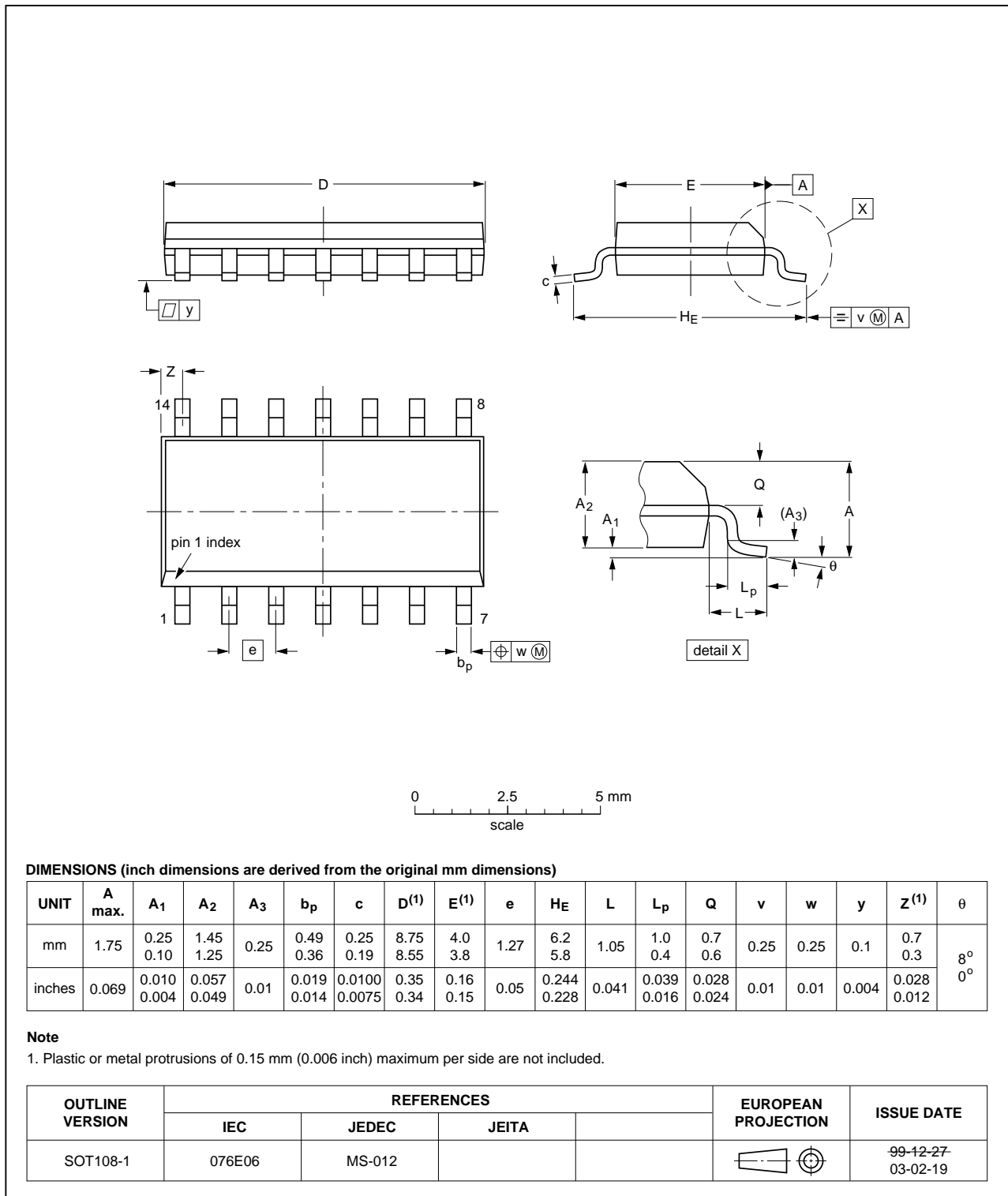


Fig 11. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

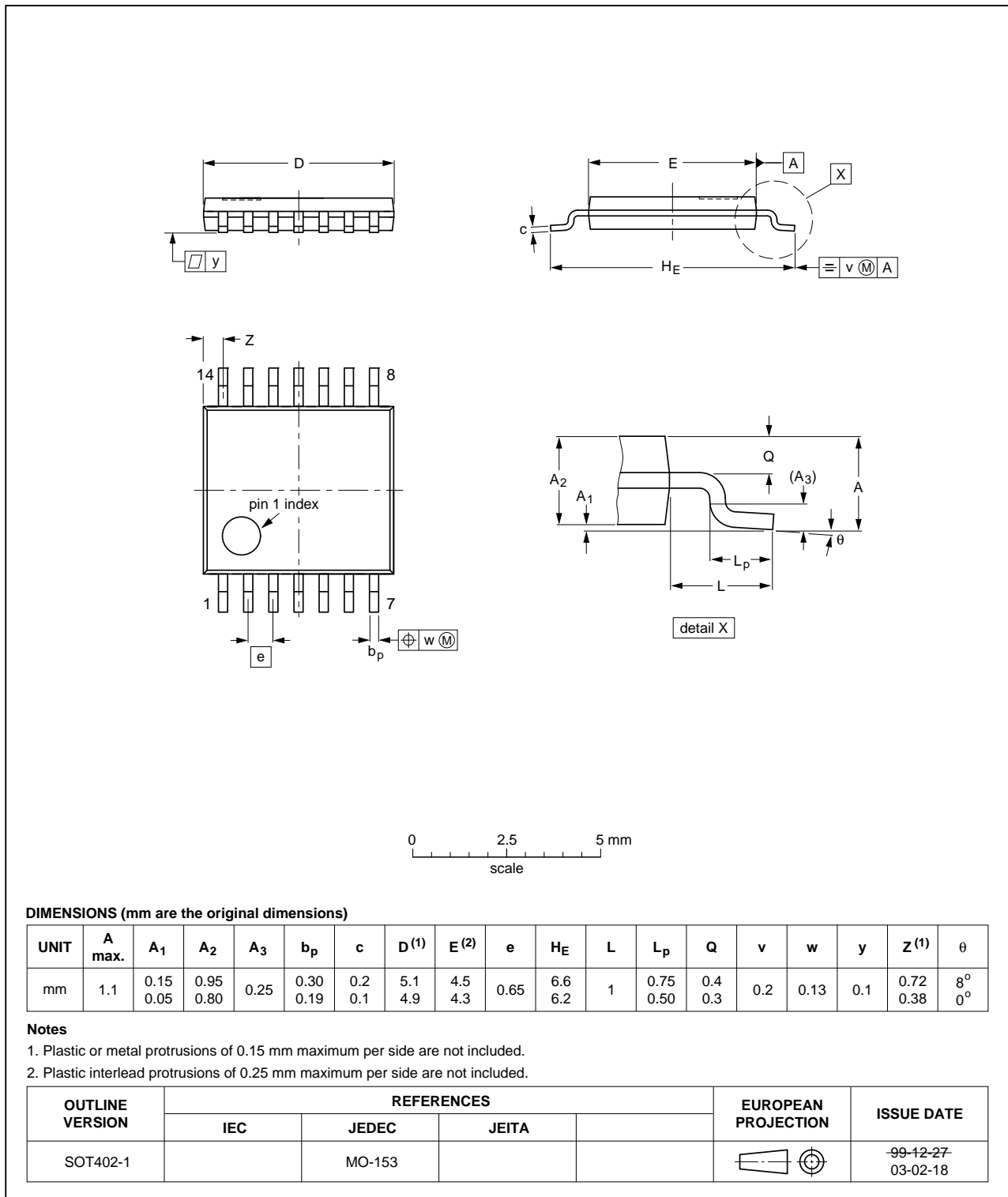
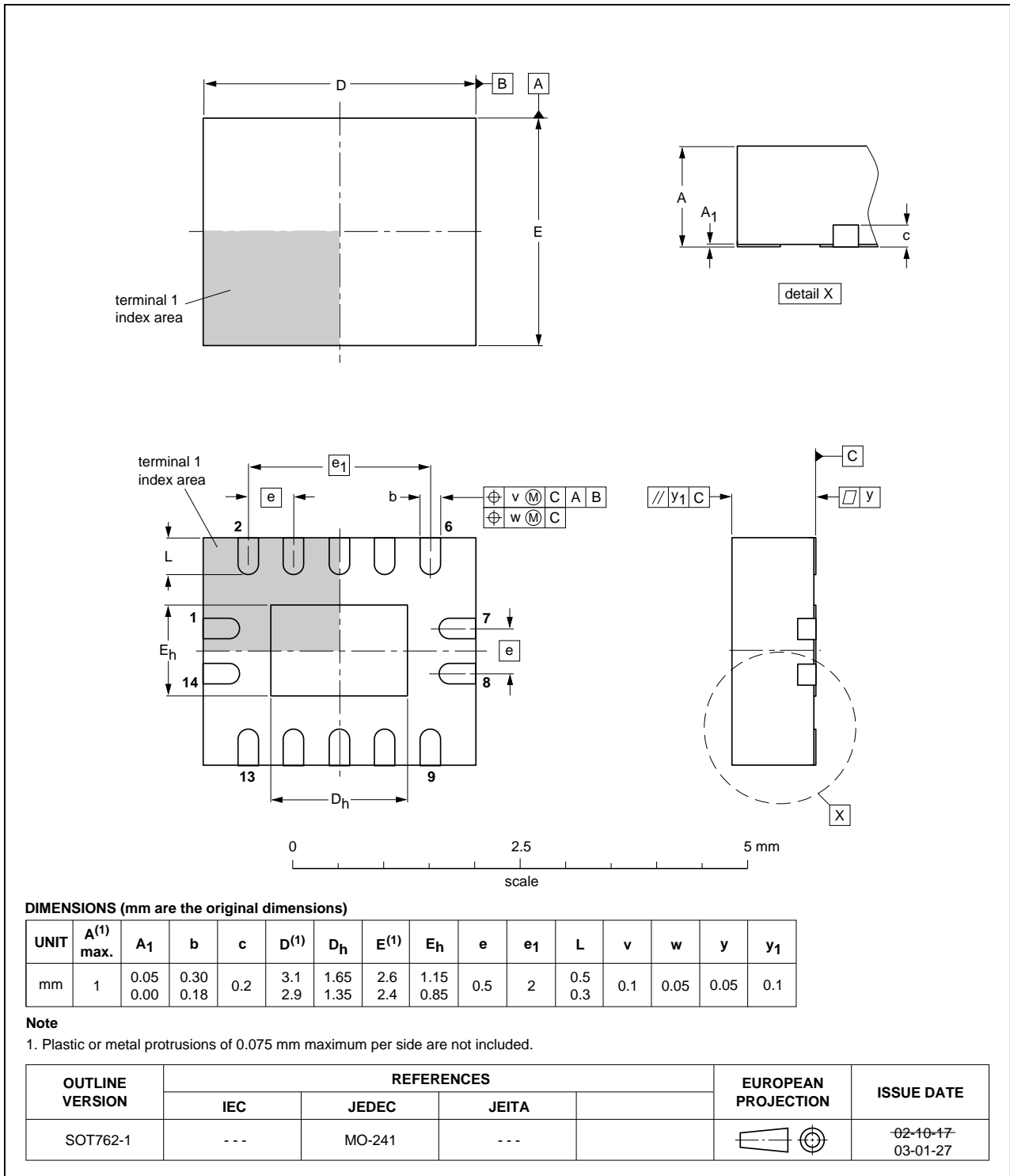


Fig 12. Package outline SOT402-1 (TSSOP14)

**DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm**

**SOT762-1**



**Fig 13. Package outline SOT762-1 (DHVQFN14)**

## 12. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

## 13. Revision history

**Table 11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT164_Q100 v.1	20130816	Product data sheet	-	-

## 14. Legal information

### 14.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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